

### IN THE DRAWINGS

Corrected drawings are supplied herewith. The currently submitted set of formal drawings corrects several minor errors in the set of formal drawings previously filed on October 22, 2001. (The original application was filed with informal drawings.) In addition, several substantive changes are proposed to FIGS. 3 and 4 without adding any new matter.

In FIG. 2, the phrase "(PRIOR ART)" has been added.

In FIG. 3, cross-hatching has been added to traces 125 and 131, as well as to several other traces. Cross-hatching has also been added to via 126, as well as to several other vias. Brackets 114 and 115 have been added. Reference numerals 113 and 129 have also been added.

In FIG. 4, a dashed line has been added along the top of rectangle 110. The phrase "PCB" has been added. Bracket 134 and dashed outline 135 have been added. Reference numeral 129 has been added.

In FIGS. 5-7 and 9, lands 528 have been shown in dashed line.

In FIG. 10, a lead line has been added to reference numeral "520".

In FIG. 11, the wording within the top of block 602 has been amended to "FORM A THIN FLEXIBLE SUBSTRATE".

In FIG. 12A, wording has been added at the top of block 702 reading "FORM A THIN FLEXIBLE SUBSTRATE".

No new matter has been added. Except as specifically mentioned immediately below, support for these amendments may be found in the corresponding figures of the informal drawings as originally filed.

Regarding FIG. 3, support for identifying the periphery 114 of die 110, central core region 115 of die 110, power and ground solder bumps 113 of die 110, and power and ground lands 129 of substrate 120 may be found, for example, in the description of FIG. 3, as amended herewith, which in turn is supported by the original written description on page 7, lines 18-23, and on page 15, lines 11-13, and by original FIGS. 3-5

Regarding FIG. 4, support for identifying periphery 134 of "conductor region", central core region 135 of "conductor region", and power and ground lands 129 of substrate 120 may be found, for example, in the description of FIG. 3, as amended herewith, which in turn is supported

**AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111**

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by the original written description on page 7, lines 18-23, and on page 15, lines 11-13, and by original FIGS. 3-5.